

Title (en)

Reverse pulse plating method

Title (de)

Methode zum Elektroplattieren mit Umkehrpulsstrom

Title (fr)

Méthode pour placage électrolytique utilisant du courant pulsé inversé

Publication

EP 1475463 B1 20110330 (EN)

Application

EP 03258024 A 20031218

Priority

US 43597602 P 20021220

Abstract (en)

[origin: EP1475463A2] A composition and method for electroplating a metal on a substrate. The composition has a chloride to brightener concentration ratio of from 20:1 to 125:1. The method of electroplating, which employs the composition, employs pulse patterns that improve physical properties of metal surfaces.

IPC 8 full level

C25D 3/02 (2006.01); **C25D 3/38** (2006.01); **C25D 5/18** (2006.01); **C25D 7/00** (2006.01)

CPC (source: EP KR US)

C25D 3/02 (2013.01 - EP KR US); **C25D 3/38** (2013.01 - EP US); **C25D 5/18** (2013.01 - EP US)

Cited by

DE102004045451A1; DE102004045451B4; US9902044B2; US9862041B2; US9445510B2; US9526183B2; US9687962B2; US10596681B2; US9878382B2; US10137514B2; US10583506B2

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 1475463 A2 20041110; **EP 1475463 A3 20060412**; **EP 1475463 B1 20110330**; **EP 1475463 B2 20170301**; CN 1540040 A 20041027; CN 1540040 B 20120404; DE 60336539 D1 20110512; JP 2004204351 A 20040722; JP 4342294 B2 20091014; KR 101085005 B1 20111121; KR 20040055684 A 20040626; TW 200424330 A 20041116; TW I296014 B 20080421; US 2005016858 A1 20050127; US 2006081475 A1 20060420

DOCDB simple family (application)

EP 03258024 A 20031218; CN 200310124974 A 20031219; DE 60336539 T 20031218; JP 2003423400 A 20031219; KR 20030093625 A 20031219; TW 92136071 A 20031219; US 29004005 A 20051130; US 74190803 A 20031219